



FOR IMMEDIATE RELEASE

**BREWER SCIENCE AND EV GROUP ANNOUNCE AGREEMENT ON
ZONEBOND™ TECHNOLOGY**

Enabling Commercialization of Groundbreaking Temporary Bonding and Debonding Technology

ROLLA, MO, USA and ST. FLORIAN, AUSTRIA, October 20, 2011 – Brewer Science, Inc., a global leading innovator and manufacturer of specialty materials, process solutions, and equipment for the microelectronics industry, and EV Group (EVG), a leading supplier of wafer bonding and lithography equipment for the MEMS, nanotechnology, and semiconductor markets, today announced an agreement on ZoneBOND™ technology. The agreement will enable both companies to commercialize the groundbreaking technology for customers in the temporary wafer bonding market.

The ZoneBOND™ technology provides a breakthrough approach for temporary wafer bonding, thin wafer processing, and debonding applications which overcomes the last remaining limitations associated with thin wafer processing. ZoneBOND™ technology allows the use of silicon, glass, and other carriers, is compatible with existing, field-proven adhesive platforms, and enables debonding at room temperature with virtually no vertical force being applied to the device wafer. To support grinding and backside processing at high temperatures and to allow for low-force carrier separation, ZoneBOND™ defines two distinctive zones on the carrier wafer surface with strong adhesion in the perimeter (edge zone) and minimal adhesion in the center zone. Therefore, only low separation force is required for carrier separation once the polymeric edge adhesive has been removed by solvent dissolution or other means.

“We are delighted to be able to bring the exciting ZoneBOND™ temporary bonding and debonding technology to the market,” said Dr. Terry Brewer, founder, CEO, and president of Brewer Science. Paul Lindner, executive technology director of EV Group, added, “Combining Brewer Science’s advanced material development and process integration and EVG’s field-proven equipment and process solutions, ZoneBOND™ will enable customers to achieve a quantum leap in thin wafer processing.”

About Brewer Science, Inc.

Brewer Science is a global technology leader in creating, developing, and manufacturing specialty materials, equipment, and process solutions for applications in semiconductors, advanced packaging/3-D ICs, MEMS, displays, LEDs, and printed electronics. Thirty years ago, Brewer Science invented and introduced ARC® anti-reflective coatings to the marketplace. These products have made significant enhancement to the lithography process, and Brewer Science continues to maintain a dominant role in the anti-reflective materials market through its latest technologies that continue to enable the progression of Moore’s law.

Through close collaboration with the world’s leading makers of microelectronic devices, and by continuously expanding research and development, the Brewer Science® product portfolio has grown and diversified and includes ProTEK® protective materials, WaferBOND® temporary bonding materials, the ZoneBOND™ thin wafer processing system, OptiINDEX™ high refractive index materials, OptiStack® multilayer lithography systems, ARC® anti-reflective coatings, CNTRENE® carbon nanotube materials, and Cee® laboratory-scale wafer processing equipment.

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Brewer Science drives to continuously develop and deliver revolutionary technology that enables customers to overcome critical industry challenges. The company's 30 years of in-depth knowledge and expertise in materials science, chemistry, physics, optics, modeling, and process integration distinguish it from all other material suppliers worldwide.

Learn more about Brewer Science at www.brewerscience.com.

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About EV Group

EV Group (EVG) is a world leader in wafer-processing solutions for semiconductor, MEMS and nanotechnology applications. Through close collaboration with its global customers, the company implements its flexible manufacturing model to develop reliable, high-quality, low-cost-of-ownership systems that are easily integrated into customers' fab lines. Key products include wafer bonding, lithography/nanoimprint lithography (NIL) and metrology equipment, as well as photoresist coaters, cleaners and inspection systems.

In addition to its dominant share of the market for wafer bonders, EVG holds a leading position in NIL and lithography for advanced packaging and MEMS. Other target semiconductor-related markets include silicon-on-insulator (SOI), compound semiconductor and silicon-based power-device solutions.

Founded in 1980, EVG is headquartered in St. Florian, Austria, and operates via a global customer support network, with subsidiaries in Tempe, Ariz.; Albany, N.Y.; Yokohama and Fukuoka, Japan; Seoul, Korea and Chung-Li, Taiwan. The company's unique Triple i-approach (invent - innovate - implement) is supported by a vertical integration, allowing EVG to respond quickly to new technology developments, apply the technology to manufacturing challenges and expedite device manufacturing in high volume. More information is available at www.EVGroup.com.

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